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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Examiner: W. Lindsay, Jr.

Group Art Unit: 2812

Attorney Docket No.: 3442US (96-428)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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C.F.R. § 1.8(a)(1)(ii)

Krista Weber Powell
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TECHNOLOGY CENTER 2800

RESPONSE TO RESTRICTION REQUIREMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Applicant responds to the Restriction Requirement of January 5, 2001, having an initial period of response expiring on February 5, 2001.